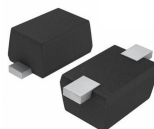


Features

Small Body Outline Dimensions:
0.039 " x 0.024 " (1.0 mm x 0.60 mm)
Low Body Height: 0.017 " (0.43 mm) Max
Stand-off Voltage: 5 V
Low Leakage
Response Time is Typically < 1 ns
ESD Rating of Class 3 per Human Body Model
IEC61000-4-2 Level 4 ESD Protection
These are Pb-Free Devices
We declare that the material of product
compliance with RoHS requirements and Halogen Free.



SOD-923



Schematic Diagram

Applications

Cellular phones audio
Digital cameras
Portable applications
Mobile telephone

Absolute Maximum Rating

Rating	Symbol	Value	Unit
IEC 61000-4-2 (ESD) Air discharge Contact discharge		±30 ±30	kV kV
Peak Pulse Power	PPK	100	W
Junction and Storage Temperature Range	TJ,TSTG	-55 to 150	°C
Lead Solder Temperature – Maximum (10 Second Duration)	TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Rating are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0*0.75*0.62 in.

Electrical Characteristics (TA=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VRWM	Reverse Working Peak Voltage				5	V
VBR	Reverse Breakdown Voltage	IT = 1mA	6	6.8	8	V
IR	Reverse Leakage Current	VRWM = 5.0 V			0.2	μA
VC	Clamping Voltage	IPP = 1 A (8/20μs)			9	V
VC	Clamping Voltage	IPP = 8 A (8/20 μs)'			12.5	V
Ipp	Peak Pulse Current	tp = 8/20μs			8	A
CJ	Capacitance	VR = 0V, f = 1MHz		50	70	pF

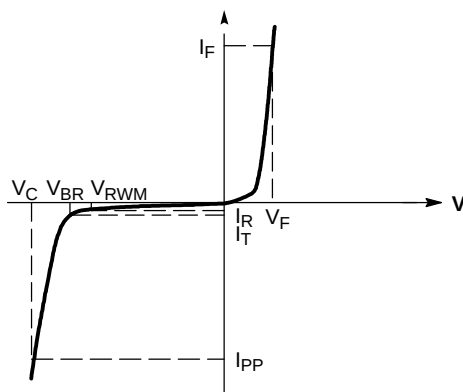
Other voltage available upon request.

2. VBR is measured with a pulse test current IT at an ambient temperature of 25°C

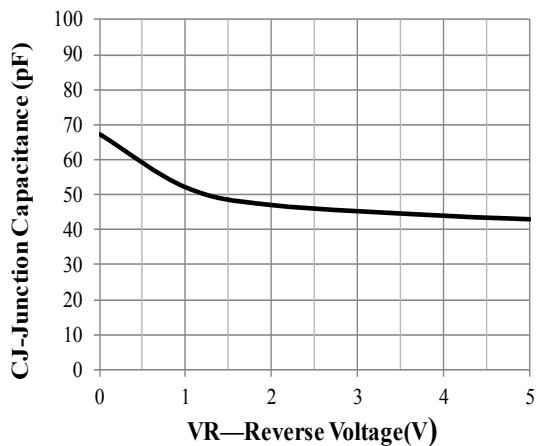
3. Surge current waveform per Figure 3.

Electrical Parameters (TA = 25°C unless otherwise noted)

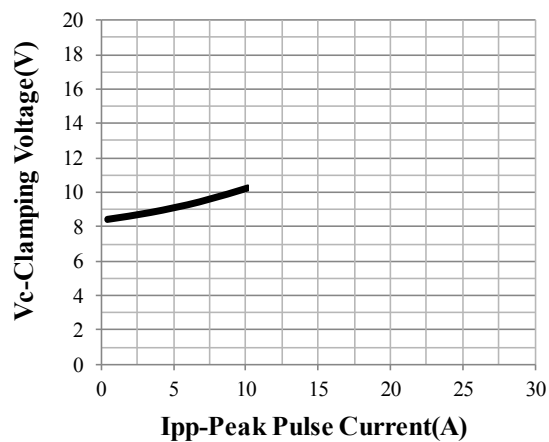
Symbol	Parameter
IPP	Maximum Reverse Peak Pulse Current
VC	Clamping Voltage @ IPP
VRWM	Working Peak Reverse Voltage
IR	Maximum Reverse Leakage Current @ VRWM
VBR	Breakdown Voltage @ IT
IT	Test Current
IF	Forward Current
VF	Forward Voltage @ IF
Ppk	Peak Power Dissipation
C	Capacitance @ VR = 0 and f = 1.0 MHz



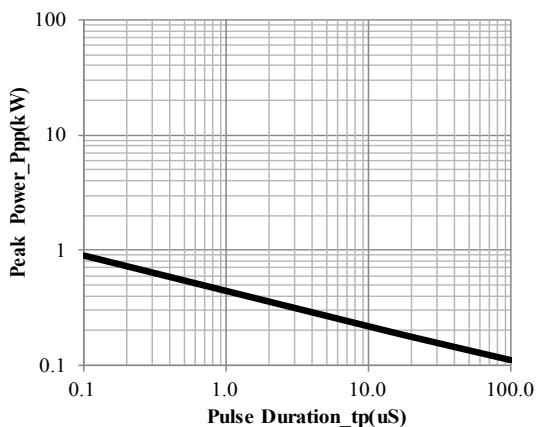
Typical Performance Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise Specified)



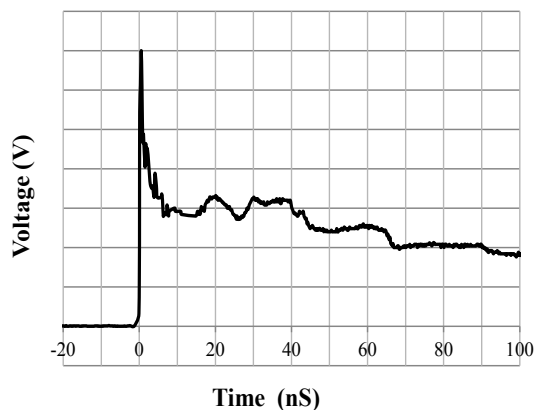
Junction Capacitance vs. Reverse Voltage



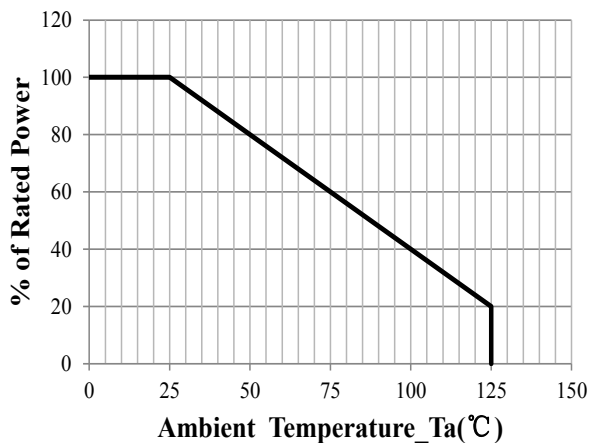
Clamping Voltage vs. Peak Pulse Current



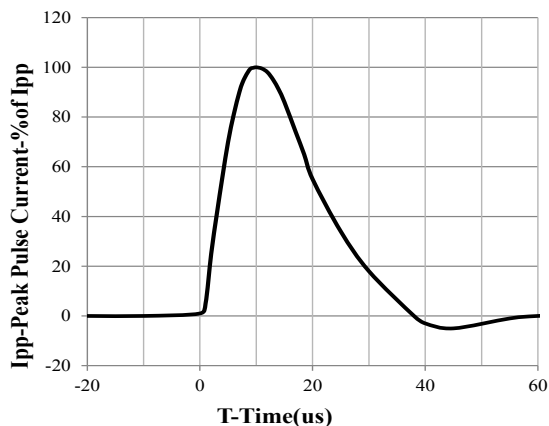
Peak Pulse Power vs. Pulse Time



IEC61000-4-2 Pulse Waveform



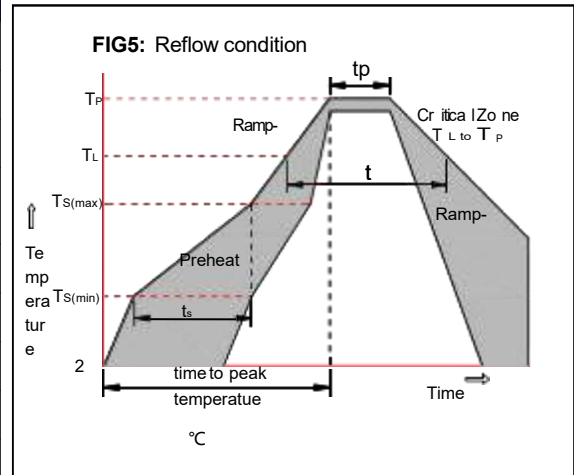
Power Derating Curve



8 X 20us Pulse Waveform

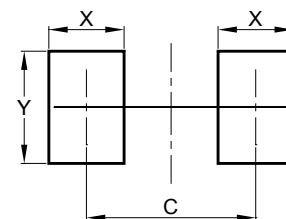
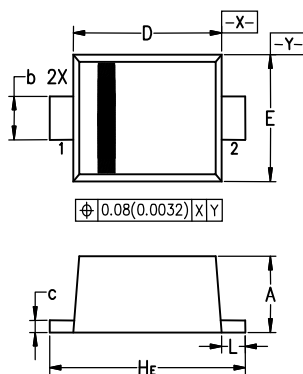
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

SOD-923

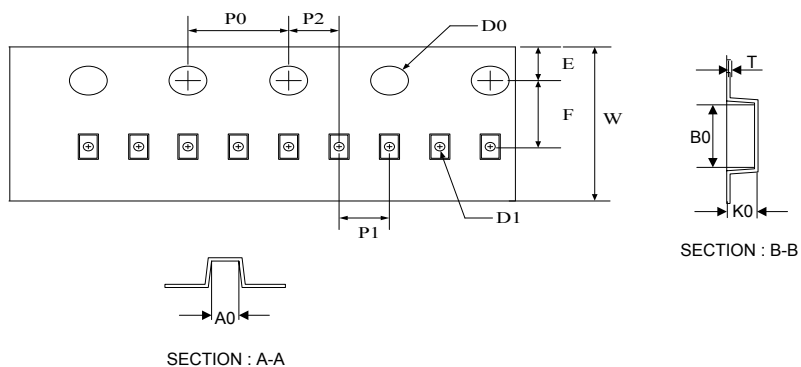


Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.014	0.016	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
H _E	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

Dimensions	Value (in mm)
C	0.950
X	0.450
Y	0.600

Tape & reel specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.20
P1	2.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	0.20±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	1.00±0.20
B0	1.35±0.20
K0	0.75±0.20
T	0.20±0.20
D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0

Quantity: 8000PCS

7" Reel

